

### Description

EW 6625B is a one-part, solvent free, thermal curing epoxy. It is ideal for component bonding, reinforcement and protection of engineering polymer substrates, such as LCP and SPS.

### Features

- Recommended substrates: FR4, LCP, SPS, glass, aluminum, stainless steel
- Both regular thermal curing and SMT reflow process curing
- Excellent resistance against moisture, weathering, as well as thermal shock and mechanical stress

### Uncured Properties

<b>Chemical Type</b>	Modified Epoxy
<b>Appearance</b>	Black
<b>Viscosity @ 25°C [mPa·s]</b> Brookfield DV2T, spindle 14# @ 5rpm	170,000
<b>Specific Gravity [g/cm<sup>3</sup>]</b>	~1.1
<b>Shelf Life @ 2-8°C [months]</b>	6
<b>Pot Life @ 25°C [hrs]</b>	48

### Curing Conditions

<b>Thermal Curing @ 150°C [mins]</b> Or reflow process	20
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### Cured Properties

<b>Hardness [Shore D]</b> ASTM D2240	72
<b>Shear Strength [MPa]</b> FR4/LCP	12
FR4/Stainless steel ASTM D1002	18

<b>Tensile Strength [MPa]</b> ASTM D638	45
<b>Elongation at Break [%]</b> ASTM D638	5
<b>Glass Transition Temperature (Tg) [°C]</b> ISO 11359	78
<b>Coefficient of Thermal Expansion (CTE) [ppm/K]</b> Below Tg	63
Above Tg ASTM D696	193

### Directions for Use

#### 1. Surface Treatment

Surfaces to be bonded should be free of dust, oil, grease or any other contaminants in order to achieve a reproducible bond. For slightly contaminated surfaces, it is sufficient to wipe with isopropanol or ethanol. Substrates with a low surface energy (e.g. polyethylene, polypropylene, Teflon) need to be pre-treated physically (e.g. atmospheric plasma or corona) in order to achieve sufficient adhesion.

#### 2. Application

Products are supplied ready for use. Depending on package type, they can be dosed manually, semi-automatically or fully-automatically with a dosage apparatus. With automatic dispensing using a cartridge, the adhesive is conveyed via pressure and a piston rod to a dispense valve. With bottles, the adhesive is conveyed using a pump.

After application, it is recommended that the two substrates be adjoined immediately as it is possible the curing process will begin with select products under ambient conditions.

#### 3. Suggested working temperature range is -40 to 150°C.

### Storage

Maximum shelf life may be obtained when product is stored in a cool, dry location at a temperature between **2°C to 8°C**.

TO PREVENT CONTAMINATION OF UNUSED PRODUCT, DO NOT RETURN ANY PRODUCT TO ITS ORIGINAL CONTAINER.

**Allow the product to thaw for two hours (30g/package) or four hours (300g/package) after it is removed from the refrigerator prior to use.** It is best practice to wipe away any moisture on the surface of the syringe with cleanroom wipes.

### Materials Handling

Refer to the Material Safety Data Sheet (MSDS) for this product.

#### *Disclaimer*

*The information provided here including the recommendations for use and application of the product is based on internal laboratory test conditions and should only be used as a reference. CollTech does not assume responsibility for the test or performance results obtained by the user. It is the responsibility of the user to perform their own evaluations to confirm whether this product is suitable for their application.*